Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

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CHO-BOND 580-208

TWO COMPONENT ELECTRICALLY CONDUCTIVE EPOXY BUS BAR ADHESIVE

Customer Value Proposition:

CHO-BOND 580-208 is a two-component, silver filled conductive epoxy adhesive system designed to be thinned and applied as an ink or spray coating. This type of application results in a uniform conductive surface with good bonding strength to a variety of substrates.

Curing of CHO-BOND 580-208 can be achieved in as little as 45 minutes with heat to minimize equipment downtime and increase manufacturing throughput. With a 1:1 weight mix ratio, CHO-BOND 580-208 is easy to handle and use. Typical applications for CHO-BOND 580-208 include bus bars and grounding of EMI shielding windows.

Features and Benefits:

Feature	Benefit
• Two component	• Fast heat cure, increases throughput, minimizes equipment downtime.
• Silver filler	• Good conductivity 0.003 ohm-cm.
• Epoxy	• 60 minute working life, works well over wide temperature range, good chemical resistance >700 psi lap shear, good for permanently bonding surfaces.
• 1:1 Weight mix ratio	• Easy to weigh out and mix
• Medium paste	• May be dispensed out of needles, fill small cracks and voids
• Material formulated to be thinned with solvent	• Easy application, material can be sprayed or screen printed for bus bars. Solvent weight mix ratio is 50:30:20, toluene:n-butanol:n-propanol.

Contact Information:

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CHO-BOND 580-208 - Product Information

Table 1 Typical Properties

CHO-BOND 580-208			
Typical Properties	**Typical Values**	**Test Method**	
Polymer	Epoxy	N/A	
Filler	Silver	N/A	
Mix Ratio, A : B (by weight)	1 : 1	N/A	
Color	Silver	N/A	(Q)
Consistency	Medium Paste	N/A	(Q)
Maximum DC Volume Resistivity (Cure Cycle 1)	0.003 ohm-cm	CHO-95-40-5101*	(Q/C)
Minimum Lap Shear Strength (Cure Cycle 1)	700 psi (4826 kPa)	CHO-95-40-5300*	(Q/C)
Specific Gravity (Room Temp Cure)	2.9	ASTM D792	(Q/C)
Hardness (Cure Cycle 1)	80 Shore D	ASTM-D2240	(Q)
Continuous Use Temperature	- 62°C to 100°C (-80 °F to 212 °F)	N/A	(Q)
Elevated Temperature Cure Cycle	**Cure Cycle Option 1:** 0.75 hours @ 100°C (212°F) **Cure Cycle Option 2:** 2.0 hours @ 66°C (150°F)	N/A	
Room Temperature Cure	24 hours	N/A	(Q)
Working Life	1.0 hour	N/A	(Q)
Shelf Life, unopened	9 months @ 25°C (77°F)	N/A	(Q)
Minimum thickness recommended	0.001 in (0.03 mm)	N/A	
Maximum thickness recommended	None	N/A	
Volatile Organic Content (VOC)	0 g/l	Calculated	
Theoretical Coverage Area at 0.010" Thick per Pound (454 grams)	9,500 in^2 (61,290 cm^2)	N/A	

Note: N/A – Not Applicable, (Q/C) - Qualification and Conformance Test, (Q) - Qualification Test
* This test Method is available from Parker Chomerics.

Table 2 Ordering Information

Product	Weight (grams)	Packaging	Part Number	Primer Included
CHO-BOND 580-208	227	2 component, 8 fluid ounce polypropylene kit	50-05-0580-0208	Not Required
	454	2 component, 16 fluid ounce polypropylene kit	50-01-0580-0208	Not Required

Please refer to Parker Chomerics Surface Preparation and CHO-BOND Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.

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TB 1141 EN January 2014

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